

MCP2551

NOTES:

1.0 DEVICE OVERVIEW

The MCP2551 is a high-speed CAN, fault-tolerant device that serves as the interface between a CAN protocol controller and the physical bus. The MCP2551 device provides differential transmit and receive capability for the CAN protocol controller, and is fully compatible with the ISO-11898 standard, including 24V requirements. It will operate at speeds of up to 1 Mb/s.

Typically, each node in a CAN system must have a device to convert the digital signals generated by a CAN controller to signals suitable for transmission over the bus cabling (differential output). It also provides a buffer between the CAN controller and the high-voltage spikes that can be generated on the CAN bus by outside sources (EMI, ESD, electrical transients, etc.).

1.1 Transmitter Function

The CAN bus has two states: Dominant and Recessive. A Dominant state occurs when the differential voltage between CANH and CANL is greater than a defined voltage (e.g., 1.2V). A Recessive state occurs when the differential voltage is less than a defined voltage (typically 0V). The Dominant and Recessive states correspond to the Low and High state of the TXD input pin, respectively. However, a Dominant state initiated by another CAN node will override a Recessive state on the CAN bus.

1.1.1 MAXIMUM NUMBER OF NODES

The MCP2551 CAN outputs will drive a minimum load of 45Ω , allowing a maximum of 112 nodes to be connected (given a minimum differential input resistance of 20 k Ω and a nominal termination resistor value of 120 Ω).

1.2 Receiver Function

The RXD output pin reflects the differential bus voltage between CANH and CANL. The Low and High states of the RXD output pin correspond to the Dominant and Recessive states of the CAN bus, respectively.

1.3 Internal Protection

CANH and CANL are protected against battery short circuits and electrical transients that can occur on the CAN bus. This feature prevents destruction of the transmitter output stage during such a fault condition.

The device is further protected from excessive current loading by thermal shutdown circuitry that disables the output drivers when the junction temperature exceeds a nominal limit of 165°C. All other parts of the chip remain operational, and the chip temperature is lowered due to the decreased power dissipation in the transmitter outputs. This protection is essential to protect against bus line short-circuit-induced damage.

1.4 Operating Modes

The Rs pin allows three modes of operation to be selected:

- High-Speed
- Slope-Control
- Standby

These modes are summarized in [Table 1-1](#).

When in High-Speed or Slope-Control mode, the drivers for the CANH and CANL signals are internally regulated to provide controlled symmetry in order to minimize EMI emissions.

Additionally, the slope of the signal transitions on CANH and CANL can be controlled with a resistor connected from pin 8 (Rs) to ground. The slope must be proportional to the current output at Rs, which will further reduce EMI emissions.

1.4.1 HIGH-SPEED

High-Speed mode is selected by connecting the Rs pin to Vss. In this mode, the transmitter output drivers have fast output rise and fall times to support high-speed CAN bus rates.

1.4.2 SLOPE-CONTROL

Slope-Control mode further reduces EMI by limiting the rise and fall times of CANH and CANL. The slope, or slew rate (SR), is controlled by connecting an external resistor (R_{EXT}) between Rs and VOL (usually ground). The slope is proportional to the current output at the Rs pin. Since the current is primarily determined by the slope-control resistance value R_{EXT}, a certain slew rate is achieved by applying a specific resistance. [Figure 1-1](#) illustrates typical slew rate values as a function of the slope-control resistance value.

1.4.3 STANDBY MODE

The device may be placed in Standby or SLEEP mode by applying a high-level to the Rs pin. In SLEEP mode, the transmitter is switched off and the receiver operates at a lower current. The receive pin on the controller side (RXD) is still functional, but will operate at a slower rate. The attached microcontroller can monitor RXD for CAN bus activity and place the transceiver into normal operation via the Rs pin (at higher bus rates, the first CAN message may be lost).

MCP2551

TABLE 1-1: MODES OF OPERATION

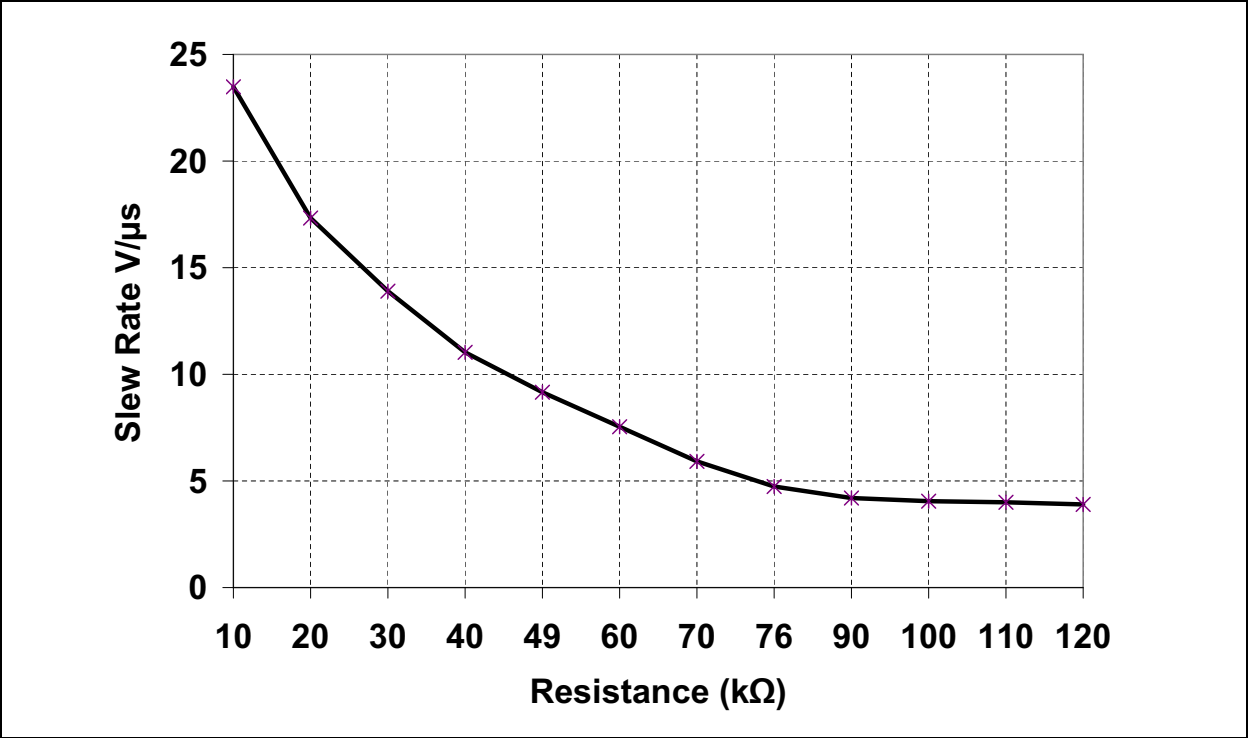
Mode	Current at R _S Pin	Resulting Voltage at R _S Pin
Standby	-I _{RS} < 10 μA	V _{RS} > 0.75 V _{DD}
Slope-Control	10 μA < -I _{RS} < 200 μA	0.4 V _{DD} < V _{RS} < 0.6 V _{DD}
High-Speed	-I _{RS} < 610 μA	0 < V _{RS} < 0.3V _{DD}

TABLE 1-2: TRANSCEIVER TRUTH TABLE

V _{DD}	V _{RS}	TXD	CANH	CANL	Bus State ⁽¹⁾	RxD ⁽¹⁾
4.5V ≤ V _{DD} ≤ 5.5V	V _{RS} < 0.75 V _{DD}	0	HIGH	LOW	Dominant	0
		1 or floating	Not Driven	Not Driven	Recessive	1
	V _{RS} > 0.75 V _{DD}	X	Not Driven	Not Driven	Recessive	1
V _{POR} < V _{DD} < 4.5V (See Note 3)	V _{RS} < 0.75 V _{DD}	0	HIGH	LOW	Dominant	0
		1 or floating	Not Driven	Not Driven	Recessive	1
	V _{RS} > 0.75 V _{DD}	X	Not Driven	Not Driven	Recessive	1
0 < V _{DD} < V _{POR}	X	X	Not Driven/ No Load	Not Driven/ No Load	High Impedance	X

- Note 1:** If another bus node is transmitting a Dominant bit on the CAN bus, then RXD is a logic '0'.
2: X = "don't care".
3: Device drivers will function, although outputs are not ensured to meet the ISO-11898 specification.

FIGURE 1-1: SLEW RATE VS. SLOPE-CONTROL RESISTANCE VALUE



1.5 TXD Permanent Dominant Detection

If the MCP2551 detects an extended Low state on the TXD input, it will disable the CANH and CANL output drivers in order to prevent the corruption of data on the CAN bus. The drivers are disabled if TXD is Low for more than 1.25 ms (minimum). This implies a maximum bit time of 62.5 μ s (16 kb/s bus rate), allowing up to 20 consecutive transmitted Dominant bits during a multiple bit error and error frame scenario. The drivers remain disabled as long as TXD remains Low. A rising edge on TXD will reset the timer logic and enable the CANH and CANL output drivers.

1.6 Power-on Reset

When the device is powered on, CANH and CANL remain in a high-impedance state until VDD reaches the voltage level VPORH. In addition, CANH and CANL will remain in a high-impedance state if TXD is Low when VDD reaches VPORH. CANH and CANL will become active only after TXD is asserted High. Once powered on, CANH and CANL will enter a high-impedance state if the voltage level at VDD falls below VPORL, providing voltage brown-out protection during normal operation.

1.7 Pin Descriptions

The 8-pin pinout is listed in [Table 1-3](#).

TABLE 1-3: MCP2551 PINOUT

Pin Number	Pin Name	Pin Function
1	TXD	Transmit Data Input
2	VSS	Ground
3	VDD	Supply Voltage
4	RXD	Receive Data Output
5	VREF	Reference Output Voltage
6	CANL	CAN Low-Level Voltage I/O
7	CANH	CAN High-Level Voltage I/O
8	Rs	Slope-Control Input

1.7.1 TRANSMITTER DATA INPUT (TXD)

TXD is a TTL-compatible input pin. The data on this pin is driven out on the CANH and CANL differential output pins. It is usually connected to the transmitter data output of the CAN controller device. When TXD is low, CANH and CANL are in the Dominant state. When TXD is high, CANH and CANL are in the Recessive state, provided that another CAN node is not driving the CAN bus with a Dominant state. TXD has an internal pull-up resistor (nominal 25 k Ω to VDD).

1.7.2 GROUND SUPPLY (VSS)

Ground supply pin.

1.7.3 SUPPLY VOLTAGE (VDD)

Positive supply voltage pin.

1.7.4 RECEIVER DATA OUTPUT (RXD)

RXD is a CMOS-compatible output that drives high or low depending on the differential signals on the CANH and CANL pins and is usually connected to the receiver data input of the CAN controller device. RXD is High when the CAN bus is Recessive and Low in the Dominant state.

1.7.5 REFERENCE VOLTAGE (VREF)

Reference Voltage Output (defined as VDD/2).

1.7.6 CAN LOW (CANL)

The CANL output drives the low side of the CAN differential bus. This pin is also tied internally to the receive input comparator.

1.7.7 CAN HIGH (CANH)

The CANH output drives the high side of the CAN differential bus. This pin is also tied internally to the receive input comparator.

1.7.8 SLOPE RESISTOR INPUT (Rs)

The Rs pin is used to select High-Speed, Slope-Control or Standby modes via an external biasing resistor.

MCP2551

NOTES:

2.0 ELECTRICAL CHARACTERISTICS

2.1 Terms and Definitions

A number of terms are defined in ISO-11898 that are used to describe the electrical characteristics of a CAN transceiver device. These terms and definitions are summarized in this section.

2.1.1 BUS VOLTAGE

V_{CANL} and V_{CANH} denote the voltages of the bus line wires CANL and CANH relative to ground of each individual CAN node.

2.1.2 COMMON MODE BUS VOLTAGE RANGE

Boundary voltage levels of V_{CANL} and V_{CANH} with respect to ground, for which proper operation will occur, if up to the maximum number of CAN nodes are connected to the bus.

2.1.3 DIFFERENTIAL INTERNAL CAPACITANCE, C_{DIFF} (OF A CAN NODE)

Capacitance seen between CANL and CANH during the Recessive state when the CAN node is disconnected from the bus (see [Figure 2-1](#)).

2.1.4 DIFFERENTIAL INTERNAL RESISTANCE, R_{DIFF} (OF A CAN NODE)

Resistance seen between CANL and CANH during the Recessive state when the CAN node is disconnected from the bus (see [Figure 2-1](#)).

2.1.5 DIFFERENTIAL VOLTAGE, V_{DIFF} (OF CAN BUS)

Differential voltage of the two-wire CAN bus, value $V_{DIFF} = V_{CANH} - V_{CANL}$.

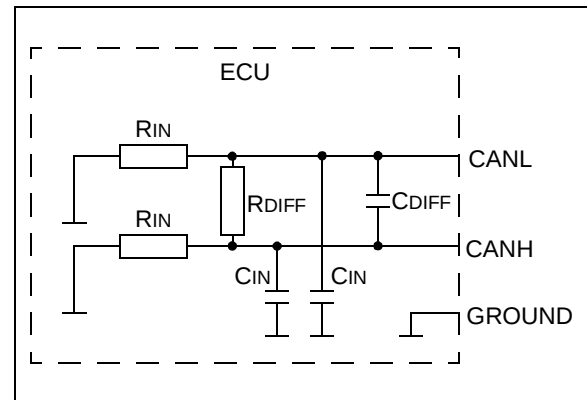
2.1.6 INTERNAL CAPACITANCE, C_{IN} (OF A CAN NODE)

Capacitance seen between CANL (or CANH) and ground during the Recessive state when the CAN node is disconnected from the bus (see [Figure 2-1](#)).

2.1.7 INTERNAL RESISTANCE, R_{IN} (OF A CAN NODE)

Resistance seen between CANL (or CANH) and ground during the Recessive state when the CAN node is disconnected from the bus (see [Figure 2-1](#)).

FIGURE 2-1: PHYSICAL LAYER DEFINITIONS



MCP2551

Absolute Maximum Ratings†

VDD	7.0V
DC Voltage at TXD, RXD, VREF and VS	-0.3V to VDD + 0.3V
DC Voltage at CANH, CANL (Note 1)	-42V to +42V
Transient Voltage on Pins 6 and 7 (Note 2)	-250V to +250V
Storage temperature	-55°C to +150°C
Operating ambient temperature	-40°C to +125°C
Virtual Junction Temperature, Tvj (Note 3)	-40°C to +150°C
Soldering temperature of leads (10 seconds)	+300°C
ESD protection on CANH and CANL pins (Note 4)	6 kV
ESD protection on all other pins (Note 4)	4 kV

Note 1: Short-circuit applied when TXD is High and Low.

- 2:** In accordance with ISO-7637.
- 3:** In accordance with IEC 60747-1.
- 4:** Classification A: Human Body Model.

† **NOTICE:** Stresses above those listed under “Maximum ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2.2 DC Characteristics

DC Specifications			Electrical Characteristics:			
			Industrial (I): T _{AMB} = -40°C to +85°C V _{DD} = 4.5V to 5.5V			
			Extended (E): T _{AMB} = -40°C to +125°C V _{DD} = 4.5V to 5.5V			
Param No.	Sym	Characteristic	Min	Max	Units	Conditions
Supply						
D1	IDD	Supply Current	—	75	mA	Dominant; V _{TXD} = 0.8V; V _{DD}
D2			—	10	mA	Recessive; V _{TXD} = +2V; R _S = 47 kΩ
D3			—	365	μA	-40°C ≤ T _{AMB} ≤ +85°C, Standby; (Note 2)
			—	465	μA	-40°C ≤ T _{AMB} ≤ +125°C, Standby; (Note 2)
D4	V _{PORH}	High-level of the Power-on Reset comparator	3.8	4.3	V	CANH, CANL outputs are active when V _{DD} > V _{PORH}
D5	V _{PORL}	Low-level of the Power-on Reset comparator	3.4	4.0	V	CANH, CANL outputs are not active when V _{DD} < V _{PORL}
D6	V _{PORD}	Hysteresis of Power-on Reset comparator	0.3	0.8	V	Note 1
Bus Line (CANH; CANL) Transmitter						
D7	V _{CANH(r)} ; V _{CANL(r)}	CANH, CANL Recessive bus voltage	2.0	3.0	V	V _{TXD} = V _{DD} ; no load.
D8	I _{O(CANH)(reces)} I _{O(CANL)(reces)}	Recessive output current	-2	+2	mA	-2V < V(CAHL,CANH) < +7V, 0V < V _{DD} < 5.5V
D9			-10	+10	mA	-5V < V(CANL,CANH) < +40V, 0V < V _{DD} < 5.5V
D10	V _{O(CANH)}	CANH Dominant output voltage	2.75	4.5	V	V _{TXD} = 0.8V
D11	V _{O(CANL)}	CANL Dominant output voltage	0.5	2.25	V	V _{TXD} = 0.8V
D12	V _{DIFF(r)(o)}	Recessive differential output voltage	-500	+50	mV	V _{TXD} = 2V; no load
D13	V _{DIFF(d)(o)}	Dominant differential output voltage	1.5	3.0	V	V _{TXD} = 0.8V; V _{DD} = 5V 40W < R _L < 60W (Note 2)
D14	I _{O(SC)(CANH)}	CANH short-circuit output current	—	-200	mA	V _{CANH} = -5V
D15			—	-100 (typical)	mA	V _{CANH} = -40V, +40V. (Note 1)
D16	I _{O(SC)(CANL)}	CANL short-circuit output current	—	200	mA	V _{CANL} = -40V, +40V. (Note 1)
D17	V _{DIFF(r)(i)}	Recessive differential input voltage	-1.0	+0.5	V	-2V < V(CANL, CANH) < +7V (Note 3)
			-1.0	+0.4	V	-12V < V(CANL, CANH) < +12V (Note 3)

Note 1: This parameter is periodically sampled and not 100% tested.

2: $I_{TXD} = I_{RXD} = I_{VREF} = 0\text{ mA}$; $0\text{V} < V_{CANL} < V_{DD}$; $0\text{V} < V_{CANH} < V_{DD}$; $V_{RS} = V_{DD}$.

3: This is valid for the receiver in all modes; High-speed, Slope-control and Standby.

MCP2551

2.2 DC Characteristics (Continued)

DC Specifications (Continued)			Electrical Characteristics:			
			Industrial (I): $T_{AMB} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $V_{DD} = 4.5\text{V}$ to 5.5V			
			Extended (E): $T_{AMB} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ $V_{DD} = 4.5\text{V}$ to 5.5V			
Param No.	Sym	Characteristic	Min	Max	Units	Conditions
Bus Line (CANH; CANL) Receiver: [TXD = 2V; pins 6 and 7 externally driven]						
D18	$V_{DIFF(d)(i)}$	Dominant differential input voltage	0.9	5.0	V	$-2\text{V} < V(\text{CANL}, \text{CANH}) < +7\text{V}$ (Note 3)
			1.0	5.0	V	$-12\text{V} < V(\text{CANL}, \text{CANH}) < +12\text{V}$ (Note 3)
D19	$V_{DIFF(h)(i)}$	Differential input hysteresis	100	200	mV	See Figure 2-3 (Note 1)
D20	R_{IN}	CANH, CANL Common-mode input resistance	5	50	k Ω	
D21	$R_{IN(d)}$	Deviation between CANH and CANL Common-mode input resistance	-3	+3	%	$V_{CANH} = V_{CANL}$
Bus Line (CANH; CANL) Receiver: [TXD = 2V; pins 6 and 7 externally driven]						
D22	R_{DIFF}	Differential input resistance	20	100	k Ω	
D24	I_{LI}	CANH, CANL input leakage current	—	150	μA	$V_{DD} < V_{POR}$; $V_{CANH} = V_{CANL} = +5\text{V}$
Transmitter Data Input (TXD)						
D25	V_{IH}	High-level input voltage	2.0	V_{DD}	V	Output Recessive
D26	V_{IL}	Low-level input voltage	V_{SS}	+0.8	V	Output Dominant
D27	I_{IH}	High-level input current	-1	+1	μA	$V_{TXD} = V_{DD}$
D28	I_{IL}	Low-level input current	-100	-400	μA	$V_{TXD} = 0\text{V}$
Receiver Data Output (RXD)						
D31	V_{OH}	High-level output voltage	$0.7 V_{DD}$	—	V	$I_{OH} = 8\text{ mA}$
D32	V_{OL}	Low-level output voltage	—	0.8	V	$I_{OL} = 8\text{ mA}$
Voltage Reference Output (VREF)						
D33	V_{REF}	Reference output voltage	$0.45 V_{DD}$	$0.55 V_{DD}$	V	$-50\text{ }\mu\text{A} < I_{VREF} < 50\text{ }\mu\text{A}$
Standby/Slope-Control (Rs pin)						
D34	V_{STB}	Input voltage for standby mode	$0.75 V_{DD}$	—	V	
D35	I_{SLOPE}	Slope-control mode current	-10	-200	μA	
D36	V_{SLOPE}	Slope-control mode voltage	$0.4 V_{DD}$	$0.6 V_{DD}$	V	
Thermal Shutdown						
D37	$T_{J(sd)}$	Shutdown junction temperature	155	180	$^{\circ}\text{C}$	Note 1
D38	$T_{J(h)}$	Shutdown temperature hysteresis	20	30	$^{\circ}\text{C}$	$-12\text{V} < V(\text{CANL}, \text{CANH}) < +12\text{V}$ (Note 3)

Note 1: This parameter is periodically sampled and not 100% tested.

2: $I_{TXD} = I_{RXD} = I_{VREF} = 0\text{ mA}$; $0\text{V} < V_{CANL} < V_{DD}$; $0\text{V} < V_{CANH} < V_{DD}$; $V_{RS} = V_{DD}$.

3: This is valid for the receiver in all modes; High-speed, Slope-control and Standby.

FIGURE 2-1: TEST CIRCUIT FOR ELECTRICAL CHARACTERISTICS

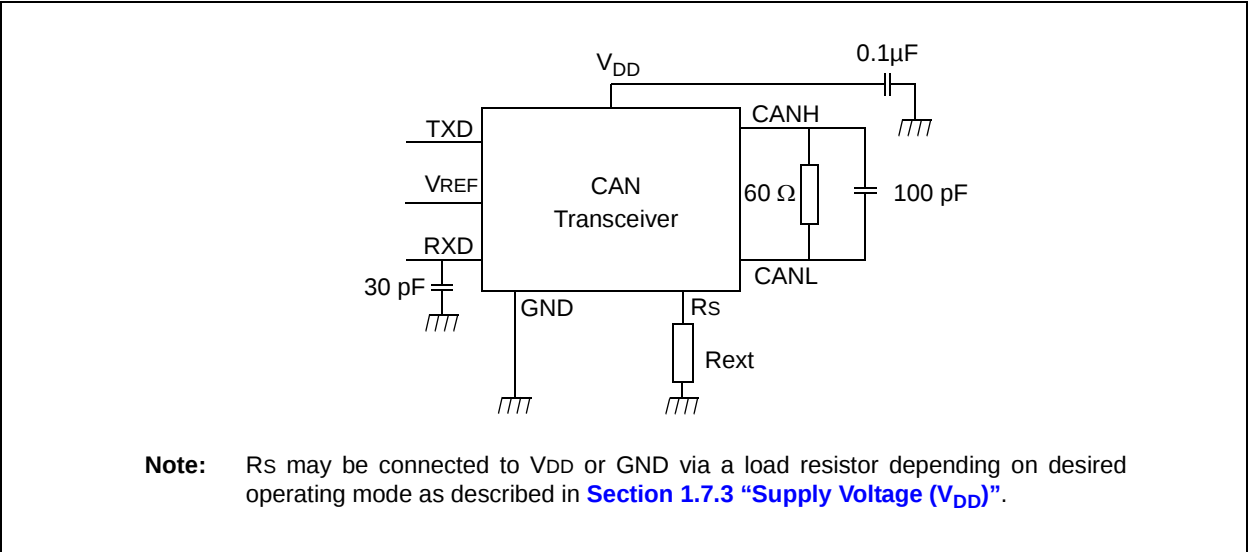


FIGURE 2-2: TEST CIRCUIT FOR AUTOMOTIVE TRANSIENTS

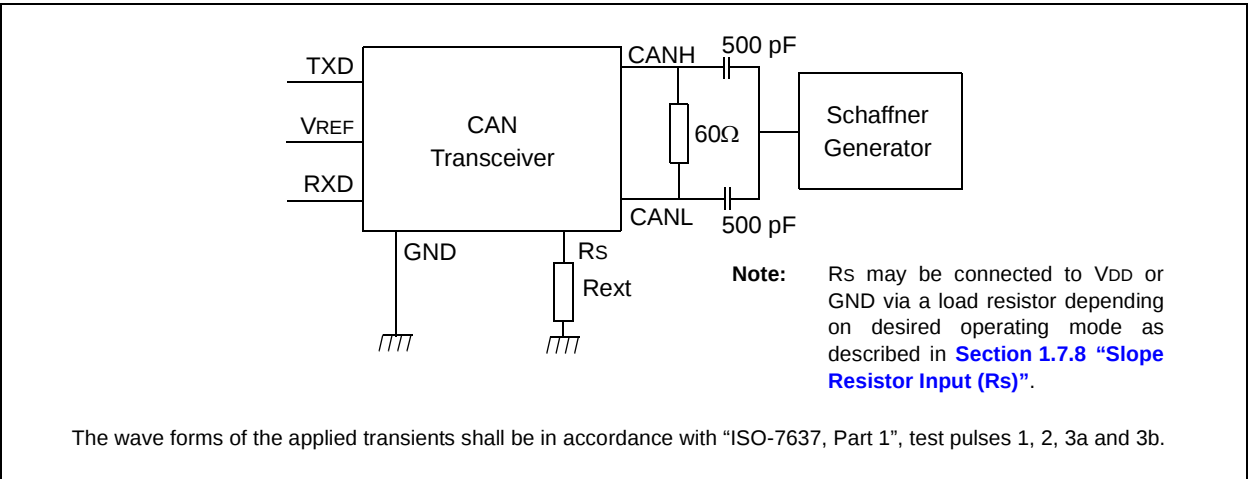
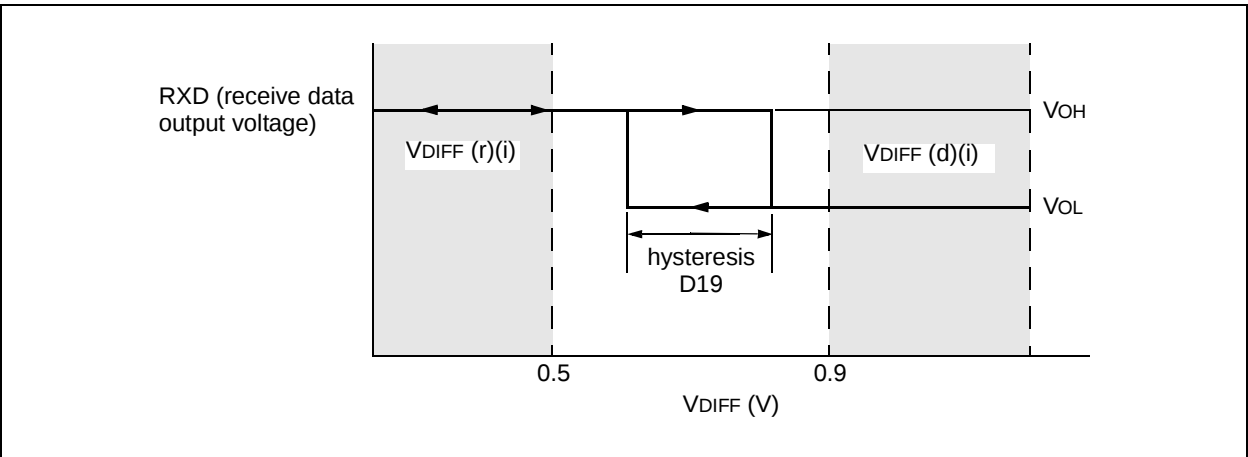


FIGURE 2-3: HYSTERESIS OF THE RECEIVER



MCP2551

2.3 AC Characteristics

AC Specifications			Electrical Characteristics:			
			Industrial (I): T _{AMB} = -40°C to +85°C V _{DD} = 4.5V to 5.5V Extended (E): T _{AMB} = -40°C to +125°C V _{DD} = 4.5V to 5.5V			
Param No.	Sym	Characteristic	Min	Max	Units	Conditions
1	tBIT	Bit time	1	62.5	μs	V _{RS} = 0V
2	fBIT	Bit frequency	16	1000	kHz	V _{RS} = 0V
3	TtxL2bus(d)	Delay TXD to bus active	—	70	ns	-40°C ≤ T _{AMB} ≤ +125°C, V _{RS} = 0V
4	TtxH2bus(r)	Delay TXD to bus inactive	—	125	ns	-40°C ≤ T _{AMB} ≤ +85°C, V _{RS} = 0V
			—	170	ns	-40°C ≤ T _{AMB} ≤ +125°C, V _{RS} = 0V
5	TtxL2rx(d)	Delay TXD to receive active	—	130	ns	-40°C ≤ T _{AMB} ≤ +125°C, V _{RS} = 0V
			—	250	ns	-40°C ≤ T _{AMB} ≤ +125°C, R _S = 47 kΩ
6	TtxH2rx(r)	Delay TXD to receiver inactive	—	175	ns	-40°C ≤ T _{AMB} ≤ +85°C, V _{RS} = 0V
			—	225	ns	-40°C ≤ T _{AMB} ≤ +85°C, R _S = 47 kΩ
			—	235	ns	-40°C ≤ T _{AMB} ≤ +125°C, V _{RS} = 0V
			—	400	ns	-40°C ≤ T _{AMB} ≤ +125°C, R _S = 47 kΩ
7	SR	CANH, CANL slew rate	5.5	8.5	V/μs	Refer to Figure 2-1 ; R _S = 47 kΩ, (Note 1)
10	twAKE	Wake-up time from standby (R _S pin)	—	5	μs	See Figure 2-5
11	TbusD2rx(s)	Bus Dominant to RXD Low (Standby mode)	—	550	ns	V _{RS} = +4V; (See Figure 2-6)
12	C _{IN} (CANH) C _{IN} (CANL)	CANH; CANL input capacitance	—	20 (typical)	pF	1 Mb/s data rate; V _{TXD} = V _{DD} , (Note 1)
13	C _{DIFF}	Differential input capacitance	—	10 (typical)	pF	1 Mb/s data rate (Note 1)
14	TtxL2busZ	TX Permanent Dominant Timer Disable Time	1.25	4	ms	
15	TtxR2pdt(res)	TX Permanent Dominant Timer Reset Time	—	1	μs	Rising edge on TXD while device is in permanent Dominant state

Note 1: This parameter is periodically sampled and not 100% tested.

2.4 Timing Diagrams and Specifications

FIGURE 2-4: TIMING DIAGRAM FOR AC CHARACTERISTICS

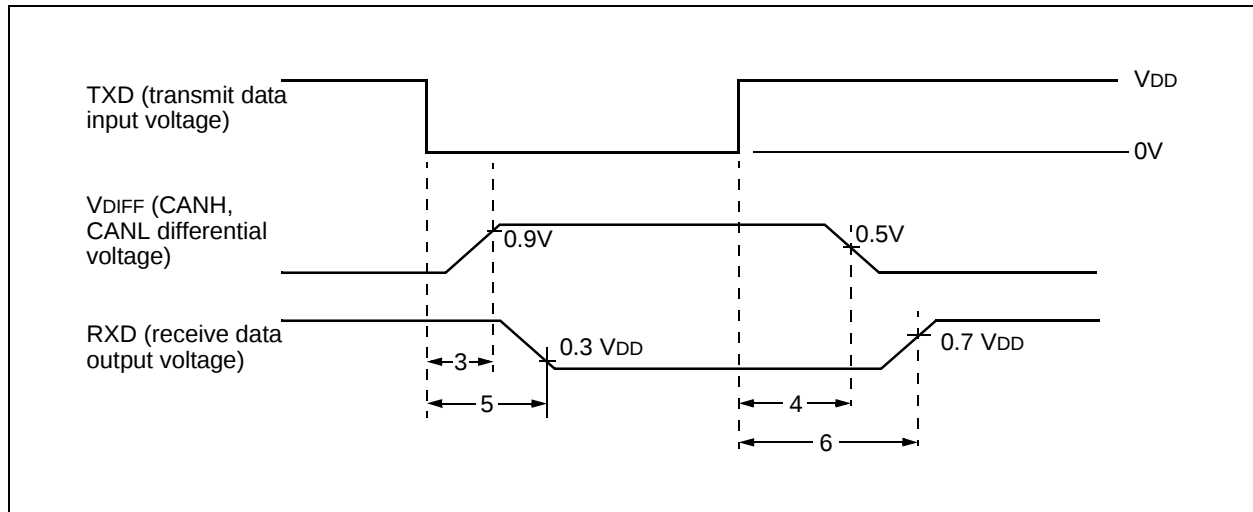


FIGURE 2-5: TIMING DIAGRAM FOR WAKE-UP FROM STANDBY

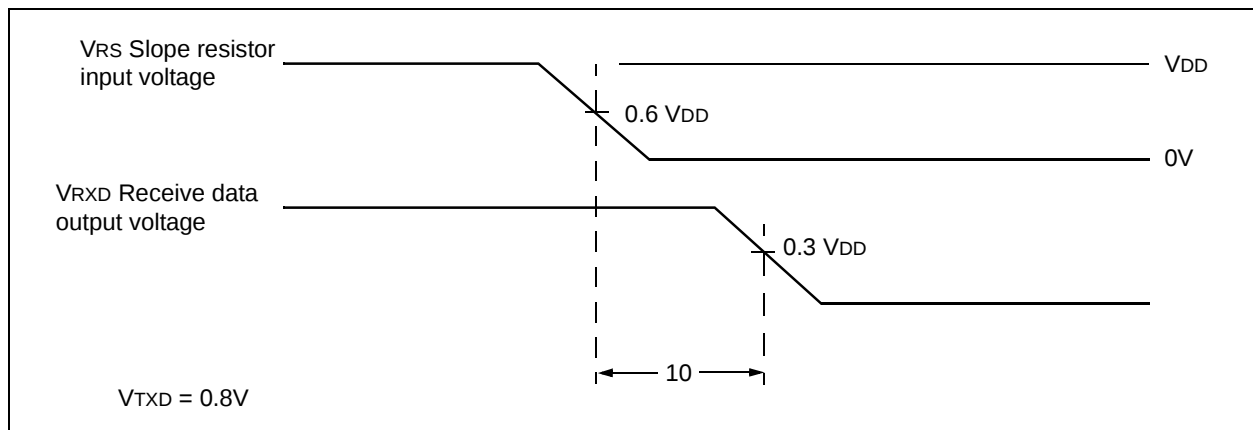
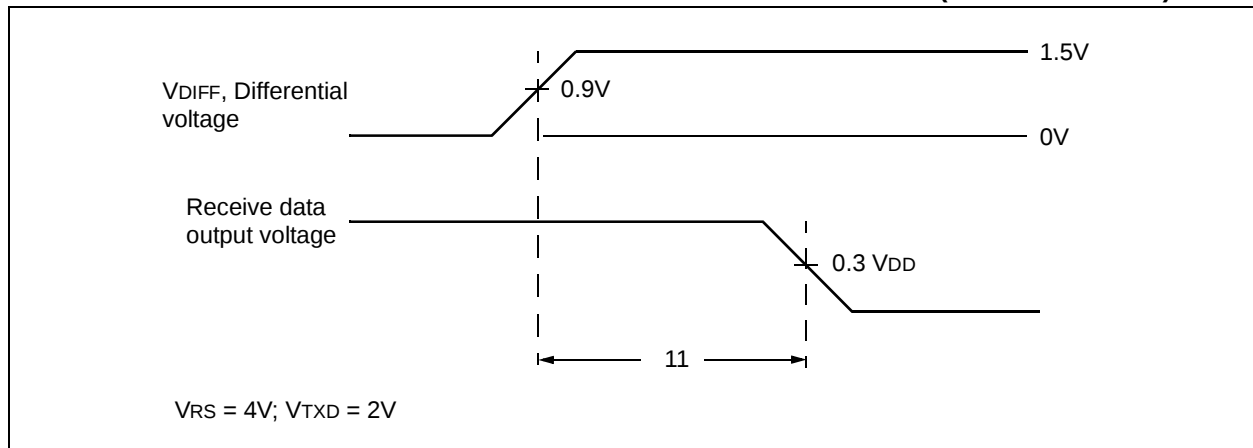


FIGURE 2-6: TIMING DIAGRAM FOR BUS DOMINANT TO RXD LOW (STANDBY MODE)



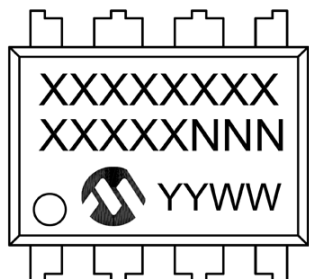
MCP2551

NOTES:

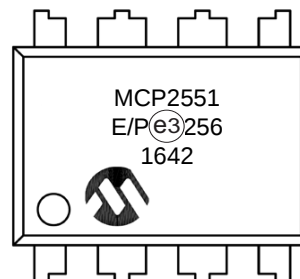
3.0 PACKAGING INFORMATION

3.1 Package Marking Information

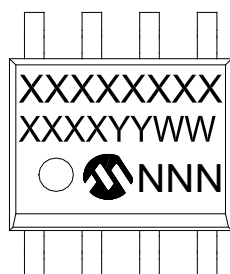
8-Lead PDIP (300 mil)



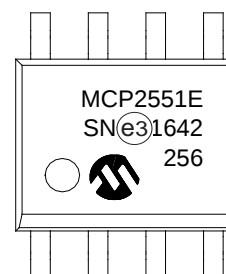
Example:



8-Lead SOIC (150 mil)



Example:



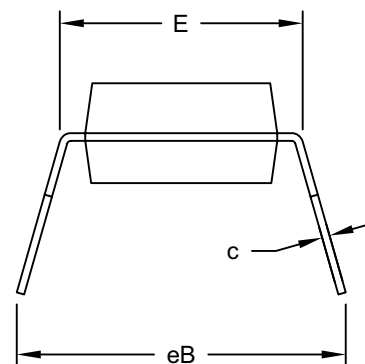
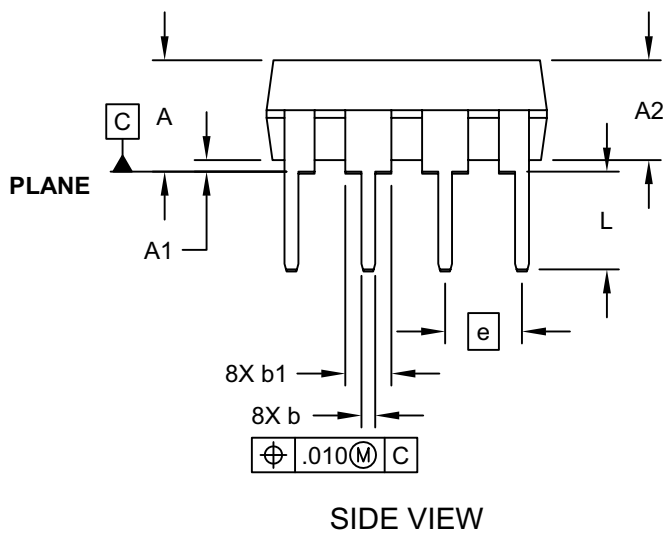
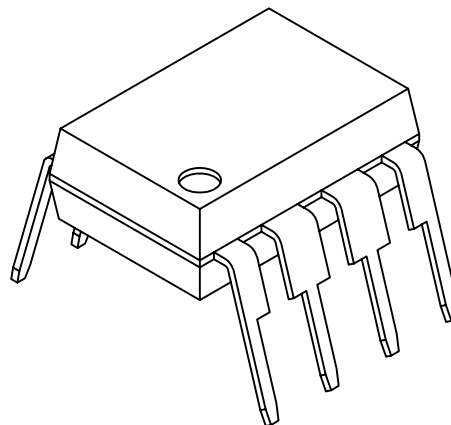
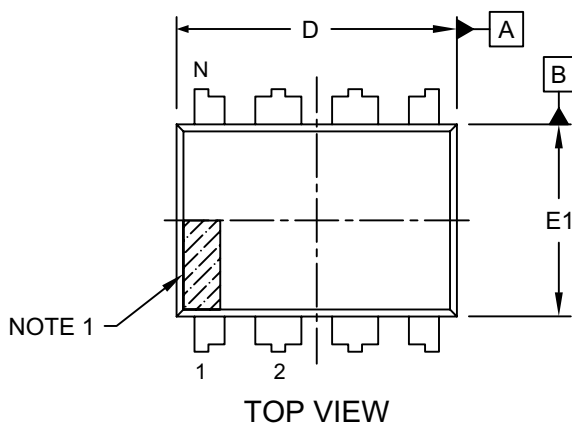
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

MCP2551

8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

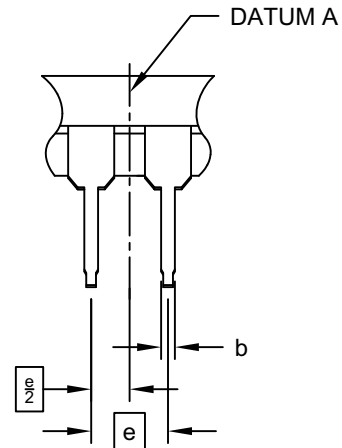
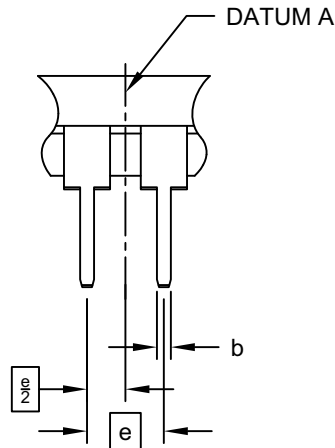


Microchip Technology Drawing No. C04-018D Sheet 1 of 2

8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

ALTERNATE LEAD DESIGN (VENDOR DEPENDENT)



		Units	INCHES		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		8		
Pitch	e		.100 BSC		
Top to Seating Plane	A		-	-	.210
Molded Package Thickness	A2		.115	.130	.195
Base to Seating Plane	A1		.015	-	-
Shoulder to Shoulder Width	E		.290	.310	.325
Molded Package Width	E1		.240	.250	.280
Overall Length	D		.348	.365	.400
Tip to Seating Plane	L		.115	.130	.150
Lead Thickness	c		.008	.010	.015
Upper Lead Width	b1		.040	.060	.070
Lower Lead Width	b		.014	.018	.022
Overall Row Spacing	§	eB	-	-	.430

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- Dimensioning and tolerancing per ASME Y14.5M

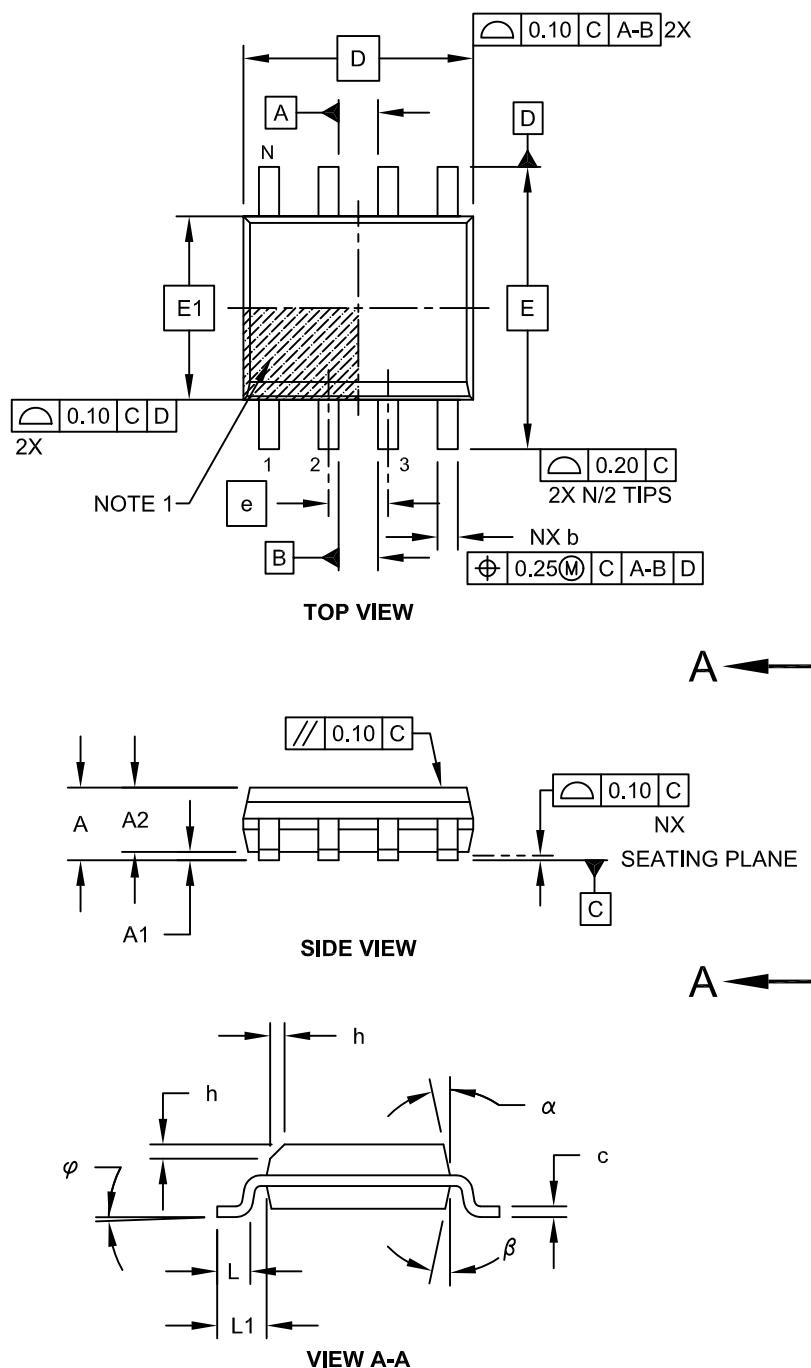
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-018D Sheet 2 of 2

MCP2551

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

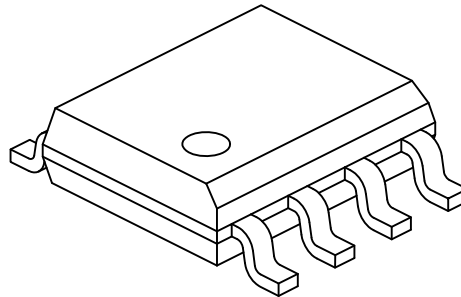
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing No. C04-057C Sheet 1 of 2

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E	6.00 BSC		
Molded Package Width	E1	3.90 BSC		
Overall Length	D	4.90 BSC		
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1	1.04 REF		
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.17	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

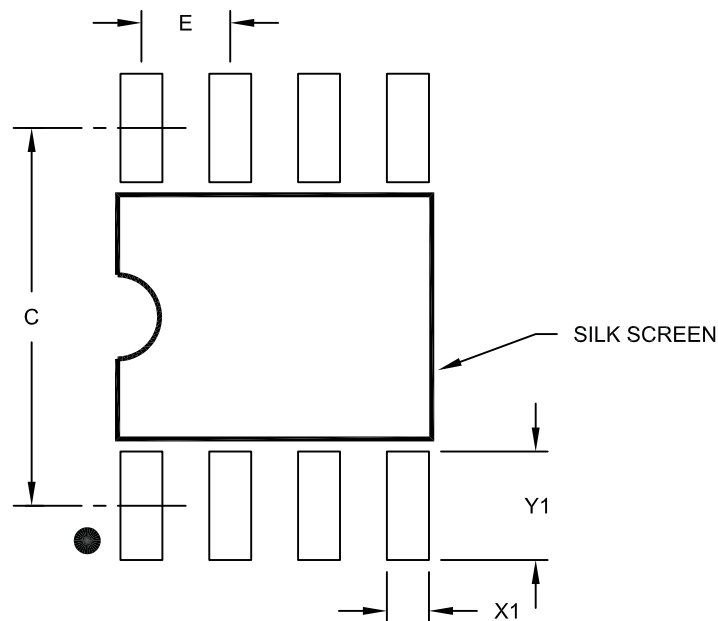
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-057C Sheet 2 of 2

MCP2551

8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A

APPENDIX A: REVISION HISTORY

Revision G (December 2016)

The following is the list of modifications:

- Added note to page 1 header: "Not recommended for new designs".
- Updated [Section 3.1 "Package Marking Information"](#).
- Minor typographical corrections.

Revision F (July 2010)

The following is the list of modifications:

- Updates to the packaging diagrams.

Revision E (January 2007)

The following is the list of modifications:

- Updates to the packaging diagrams.

Revision A (June 2001)

- Original Release of this Document.

MCP2551

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>-X</u>	<u>/XX</u>	<u>XXX</u>
Device	Temperature Range	Package	Pattern
Device:	MCP2551: High-Speed CAN Transceiver MCP2551T: High-Speed CAN Transceiver (Tape and Reel)		
Temperature Range:	I = -40°C to +85°C E = -40°C to +125°C		
Package:	P = Plastic DIP (300 mil Body) 8-lead SN = Plastic SOIC (150 mil Body) 8-lead		

Examples:

a) MCP2551-I/P: Industrial temperature, PDIP package.

b) MCP2551-E/P: Extended temperature, PDIP package.

c) MCP2551-I/SN: Industrial temperature, SOIC package.

d) MCP2551T-I/SN: Tape and Reel, Industrial Temperature, SOIC package.

e) MCP2551T-E/SN: Tape and Reel, Extended Temperature, SOIC package.

f) MCP2551-E/SN: Extended Temperature, SOIC package.

MCP2551

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
== ISO/TS 16949 ==

Trademarks

The Microchip name and logo, the Microchip logo, AnyRate, AVR, AVR logo, AVR Freaks, BeaconThings, BitCloud, CryptoMemory, CryptoRF, dsPIC, FlashFlex, flexPWR, Helder, JukeBlox, KEELOQ, KEELOQ logo, Klear, LANCheck, LINK MD, maxStylus, maxTouch, MediaLB, megaAVR, MOST, MOST logo, MPLAB, OptoLyzer, PIC, picoPower, PICSTART, PIC32 logo, Prochip Designer, QTouch, RightTouch, SAM-BA, SpyNIC, SST, SST Logo, SuperFlash, tinyAVR, UNI/O, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

ClockWorks, The Embedded Control Solutions Company, EtherSynch, Hyper Speed Control, HyperLight Load, IntellIMOS, mTouch, Precision Edge, and Quiet-Wire are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, BodyCom, chipKIT, chipKIT logo, CodeGuard, CryptoAuthentication, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, EtherGREEN, In-Circuit Serial Programming, ICSP, Inter-Chip Connectivity, JitterBlocker, KlearNet, KlearNet logo, Mindi, MiWi, motorBench, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICKit, PICtail, PureSilicon, QMatrix, RightTouch logo, REAL ICE, Ripple Blocker, SAM-ICE, Serial Quad I/O, SMART-I.S., SQI, SuperSwitcher, SuperSwitcher II, Total Endurance, TSHARC, USBCheck, VariSense, ViewSpan, WiperLock, Wireless DNA, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2001-2016, Microchip Technology Incorporated, All Rights Reserved.

ISBN: 978-1-5224-1198-7

Worldwide Sales and Service

AMERICAS

Corporate Office
 2355 West Chandler Blvd.
 Chandler, AZ 85224-6199
 Tel: 480-792-7200
 Fax: 480-792-7277
 Technical Support:
<http://www.microchip.com/support>
 Web Address:
www.microchip.com

Atlanta
 Duluth, GA
 Tel: 678-957-9614
 Fax: 678-957-1455

Austin, TX
 Tel: 512-257-3370

Boston
 Westborough, MA
 Tel: 774-760-0087
 Fax: 774-760-0088

Chicago
 Itasca, IL
 Tel: 630-285-0071
 Fax: 630-285-0075

Dallas
 Addison, TX
 Tel: 972-818-7423
 Fax: 972-818-2924

Detroit
 Novi, MI
 Tel: 248-848-4000

Houston, TX
 Tel: 281-894-5983

Indianapolis
 Noblesville, IN
 Tel: 317-773-8323
 Fax: 317-773-5453
 Tel: 317-536-2380

Los Angeles
 Mission Viejo, CA
 Tel: 949-462-9523
 Fax: 949-462-9608
 Tel: 951-273-7800

Raleigh, NC
 Tel: 919-844-7510

New York, NY
 Tel: 631-435-6000

San Jose, CA
 Tel: 408-735-9110
 Tel: 408-436-4270

Canada - Toronto
 Tel: 905-695-1980
 Fax: 905-695-2078

ASIA/PACIFIC

Asia Pacific Office
 Suites 3707-14, 37th Floor
 Tower 6, The Gateway
 Harbour City, Kowloon

Hong Kong
 Tel: 852-2943-5100
 Fax: 852-2401-3431

Australia - Sydney
 Tel: 61-2-9868-6733
 Fax: 61-2-9868-6755

China - Beijing
 Tel: 86-10-8569-7000
 Fax: 86-10-8528-2104

China - Chengdu
 Tel: 86-28-8665-5511
 Fax: 86-28-8665-7889

China - Chongqing
 Tel: 86-23-8980-9588
 Fax: 86-23-8980-9500

China - Dongguan
 Tel: 86-769-8702-9880

China - Guangzhou
 Tel: 86-20-8755-8029

China - Hangzhou
 Tel: 86-571-8792-8115
 Fax: 86-571-8792-8116

China - Hong Kong SAR
 Tel: 852-2943-5100
 Fax: 852-2401-3431

China - Nanjing
 Tel: 86-25-8473-2460
 Fax: 86-25-8473-2470

China - Qingdao
 Tel: 86-532-8502-7355
 Fax: 86-532-8502-7205

China - Shanghai
 Tel: 86-21-3326-8000
 Fax: 86-21-3326-8021

China - Shenyang
 Tel: 86-24-2334-2829
 Fax: 86-24-2334-2393

China - Shenzhen
 Tel: 86-755-8864-2200
 Fax: 86-755-8203-1760

China - Wuhan
 Tel: 86-27-5980-5300
 Fax: 86-27-5980-5118

China - Xian
 Tel: 86-29-8833-7252
 Fax: 86-29-8833-7256

ASIA/PACIFIC

China - Xiamen
 Tel: 86-592-2388138
 Fax: 86-592-2388130

China - Zhuhai
 Tel: 86-756-3210040
 Fax: 86-756-3210049

India - Bangalore
 Tel: 91-80-3090-4444
 Fax: 91-80-3090-4123

India - New Delhi
 Tel: 91-11-4160-8631
 Fax: 91-11-4160-8632

India - Pune
 Tel: 91-20-3019-1500

Japan - Osaka
 Tel: 81-6-6152-7160
 Fax: 81-6-6152-9310

Japan - Tokyo
 Tel: 81-3-6880-3770
 Fax: 81-3-6880-3771

Korea - Daegu
 Tel: 82-53-744-4301
 Fax: 82-53-744-4302

Korea - Seoul
 Tel: 82-2-554-7200
 Fax: 82-2-558-5932 or
 82-2-558-5934

Malaysia - Kuala Lumpur
 Tel: 60-3-6201-9857
 Fax: 60-3-6201-9859

Malaysia - Penang
 Tel: 60-4-227-8870
 Fax: 60-4-227-4068

Philippines - Manila
 Tel: 63-2-634-9065
 Fax: 63-2-634-9069

Singapore
 Tel: 65-6334-8870
 Fax: 65-6334-8850

Taiwan - Hsin Chu
 Tel: 886-3-5778-366
 Fax: 886-3-5770-955

Taiwan - Kaohsiung
 Tel: 886-7-213-7830

Taiwan - Taipei
 Tel: 886-2-2508-8600
 Fax: 886-2-2508-0102

Thailand - Bangkok
 Tel: 66-2-694-1351
 Fax: 66-2-694-1350

EUROPE

Austria - Wels
 Tel: 43-7242-2244-39
 Fax: 43-7242-2244-393

Denmark - Copenhagen
 Tel: 45-4450-2828
 Fax: 45-4485-2829

Finland - Espoo
 Tel: 358-9-4520-820

France - Paris
 Tel: 33-1-69-53-63-20
 Fax: 33-1-69-30-90-79

France - Saint Cloud
 Tel: 33-1-30-60-70-00

Germany - Garching
 Tel: 49-8931-9700

Germany - Haan
 Tel: 49-2129-3766400

Germany - Heilbronn
 Tel: 49-7131-67-3636

Germany - Karlsruhe
 Tel: 49-721-625370

Germany - Munich
 Tel: 49-89-627-144-0
 Fax: 49-89-627-144-44

Germany - Rosenheim
 Tel: 49-8031-354-560

Israel - Ra'anana
 Tel: 972-9-744-7705

Italy - Milan
 Tel: 39-0331-742611
 Fax: 39-0331-466781

Italy - Padova
 Tel: 39-049-7625286

Netherlands - Drunen
 Tel: 31-416-690399
 Fax: 31-416-690340

Norway - Trondheim
 Tel: 47-7289-7561

Poland - Warsaw
 Tel: 48-22-3325737

Romania - Bucharest
 Tel: 40-21-407-87-50

Spain - Madrid
 Tel: 34-91-708-08-90
 Fax: 34-91-708-08-91

Sweden - Gothenberg
 Tel: 46-31-704-60-40

Sweden - Stockholm
 Tel: 46-8-5090-4654

UK - Wokingham
 Tel: 44-118-921-5800
 Fax: 44-118-921-5820